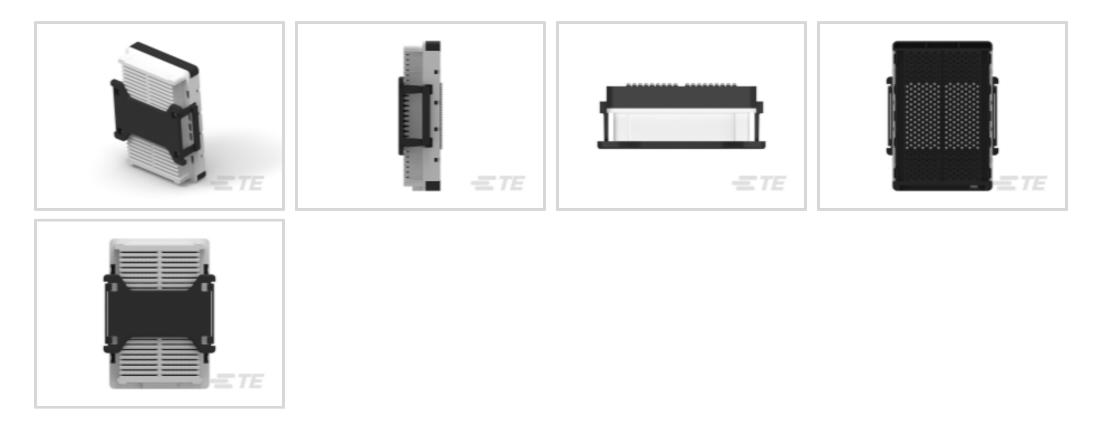
# 6-1761615-5 - ACTIVE

#### STEP-Z

TE Internal #: 6-1761615-5 PCB Mount Receptacle, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Gold, Surface Mount - Solder Ball, Power & Signal, Natural

#### View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 200

Number of Rows: 2

## Features

**E T E connectivity** 

### Product Type Features

| PCB Connector Assembly Type           | PCB Mount Receptacle  |
|---------------------------------------|-----------------------|
| Connector System                      | Board-to-Board        |
| Sealable                              | No                    |
| Connector & Contact Terminates To     | Printed Circuit Board |
| Configuration Features                |                       |
| Stackable                             | Yes                   |
| PCB Mount Orientation                 | Vertical              |
| Number of Positions                   | 200                   |
| Number of Rows                        | 2                     |
| Board-to-Board Configuration          | Parallel              |
| Electrical Characteristics            |                       |
| Dielectric Withstanding Voltage (Max) | 500 VAC               |
| Insulation Resistance                 | 18 MΩ                 |
| Operating Voltage                     | 48 VAC                |

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PCB Mount Receptacle, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Gold, Surface Mount - Solder Ball, Power & Signal, Natural



## **Body Features**

| Primary Product Color                          | Natural   |
|--|---|
| Contact Features                               |   |
| Contact Layout                                 | Matrix  |
| Mating Tab Width                               | 1 mm[.04 in]  |
| Mating Tab Thickness                           | .2 mm[.008 in]  |
| Contact Shape & Form                           | Dual Beam, Single Beam                                |
| PCB Contact Termination Area Plating Material  | Tin-Silver  |
| Contact Base Material                          | Copper Alloy  |
| Contact Mating Area Plating Material           | Gold  |
| Contact Mating Area Plating Material Thickness | .76 μm[29.9212 μin]                                   |
| Contact Type                                   | Socket  |
| Contact Current Rating (Max)                   | 1 A   |
| Termination Features                           |   |
| Termination Method to Printed Circuit Board    | Surface Mount - Solder Ball                           |
| Mechanical Attachment                          |   |
| Mating Retention                               | With  |
| Mating Alignment                               | Without   |
| PCB Mount Retention                            | Without   |
| PCB Mount Alignment                            | Without   |
| Connector Mounting Type                        | Board Mount   |
| Housing Features                               |   |
| Centerline (Pitch)                             | 1.3 mm[.051 in]                                       |
| Housing Material                               | Thermoplastic   |
| Dimensions                                     |   |
| Connector Height                               | 20.65 mm[.812 in]                                     |
| Row-to-Row Spacing                             | 2 mm[.079 in]   |
| Stack Height                                   | 25 mm, 27 mm, 28 mm, 30 mm, 35 mm, 40<br>mm[1.575 in] |
| PCB Thickness (Recommended)                    | 1.57 mm[.8 in]  |
| Usage Conditions                               |   |
| Operating Temperature Range                    | 0-100 °C[32-212 °F]                                   |

PCB Mount Receptacle, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Gold, Surface Mount - Solder Ball, Power & Signal, Natural



#### **Operation/Application**

| Assembly Process Feature   | None  |
|--|---|
| Circuit Application  | Power & Signal  |
| Industry Standards   |   |
| UL Flammability Rating   | UL 94V-0  |
| Packaging Features   |   |
| Packaging Quantity   | 25  |
| Packaging Method   | Tray  |
| <b>Product Compliance</b><br>For compliance documentation, visit the product page on TE.com> |   |
| EU RoHS Directive 2011/65/EU   | Compliant   |
| EU ELV Directive 2000/53/EC  | Compliant   |
| China RoHS 2 Directive MIIT Order No 32, 2016  | No Restricted Materials Above Threshold   |
| EU REACH Regulation (EC) No. 1907/2006   | Current ECHA Candidate List: JAN 2024<br>(240)<br>Candidate List Declared Against: JAN 2024 |

#### Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Reflow solder capable to 260°C

Does not contain REACH SVHC

#### Solder Process Capability

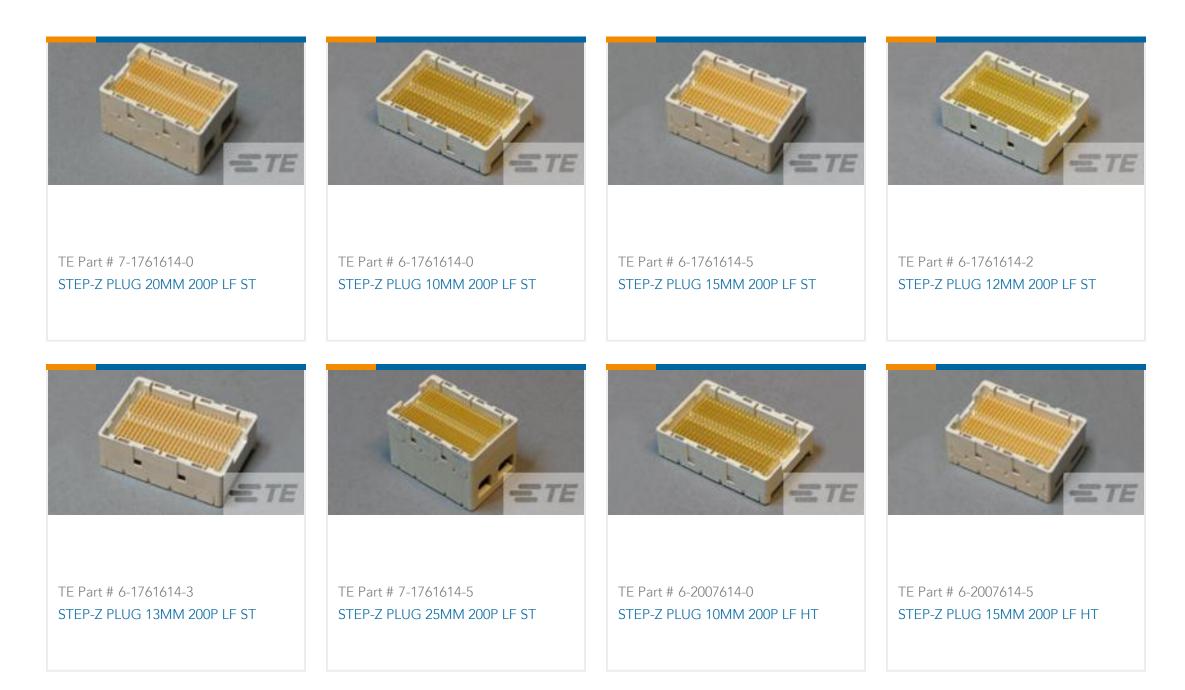
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**

PCB Mount Receptacle, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Gold, Surface Mount - Solder Ball, Power & Signal, Natural

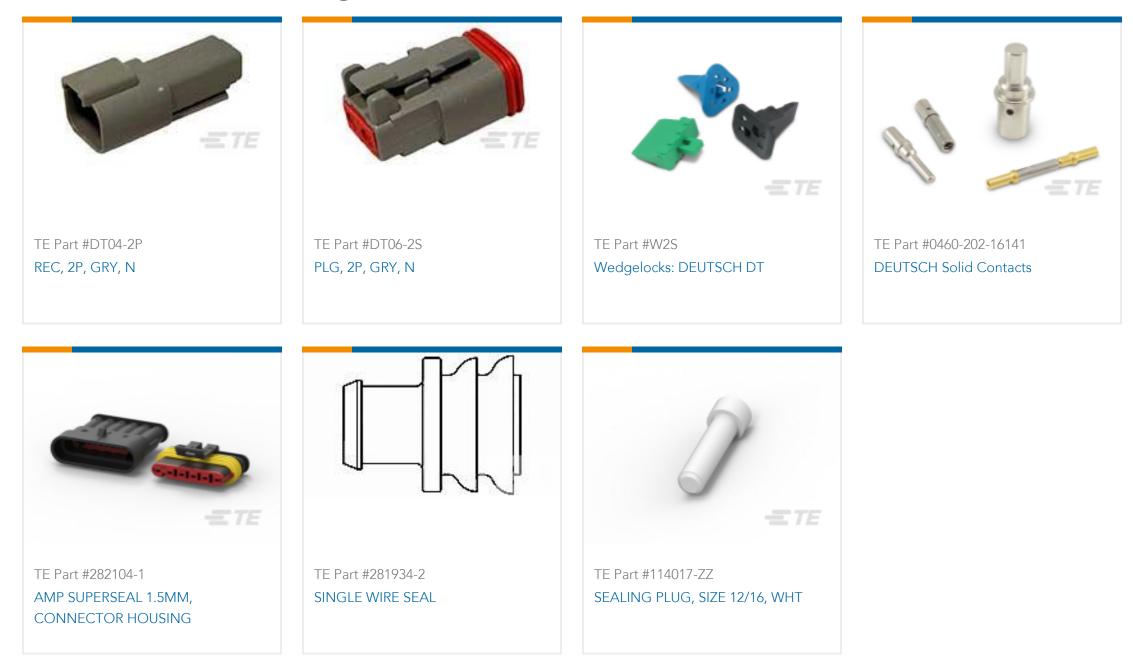






TE Part # 7-2007614-5 STEP-Z PLUG 25MM 200P LF HT

## Customers Also Bought



## Documents

PCB Mount Receptacle, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Gold, Surface Mount - Solder Ball, Power & Signal, Natural



#### **CAD** Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_6-1761615-5\_A.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_6-1761615-5\_A.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_6-1761615-5\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages STEP-Z Interconnection System

English

Product Specifications Application Specification

English